

<b>THERMAL MANAGEMENT</b>	<b>HTC</b> Non-Silicone Heat Transfer Compound	<b>HTS</b> Silicone Heat Transfer Compound	<b>HTCP</b> Non-Silicone Heat Transfer Compound Plus	<b>HTSP</b> Silicone Heat Transfer Compound Plus	<b>TBS</b> 2 Part Thermal Bonding System	<b>ER2074</b> 2 Part Epoxy	<b>TCR</b> Thermally Conductive RTV
<b>Typical Properties</b>							
<b>Base Material</b>	Non-Silicone Oil	Silicone Oil	Non-Silicone Oil	Silicone Oil	Epoxy	Epoxy	Silicone RTV
<b>Thermal Conductivity (W/mK)</b>	0.9	0.9	2.5	3	1.1	1.26	1.79
<b>Density (g/ml IP-59)</b>	2.04	2.1	3	3	2.8	2.09	2.3
<b>Temperature Range (° C)</b>	-50 to +130	-50 to +200	-50 to +130	-50 to +200	-40 to +120	-40 to +130	-50 to +250
<b>Evaporation Weight Loss (96hrs @ 100° C IP-183)</b>	=1.00%	=0.80%	=1.00%	=0.80%	N/A	N/A	N/A
<b>Dielectric Strength (kV/mm)</b>	42	18	42	18	11	10	>8
<b>Electrical Insulation Resistance (OUL746C)</b>	10 <sup>12</sup>	10 <sup>12</sup>	10 <sup>12</sup>	10 <sup>12</sup>	10 <sup>12</sup>	10 <sup>15</sup>	10 <sup>14</sup>
<b>Cure Time (Hours @ 20° C / Minutes @ 100° C)</b>	N/A	N/A	N/A	N/A	24/45	24/60	24*

\* Requires moisture to cure, elevated temperatures not recommended unless moisture is present.

**Disclaimer: All information is given in good faith but without warranty.**